

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	5	11307679.pn. or 07335814.pn. or 05251616.pn. or 6406937.pn. or 5266833.pn.	USPAT; JPO	2002/11/22 12:49
2	BRS	1	6064117.pn.	USPAT; JPO	2002/11/22 12:49
3	BRS	1	"6064117"	USPAT; JPO	2002/11/22 12:53
4	BRS	1	"5708300".PN.	USPAT	2002/11/22 12:50
5	BRS	1	"5886398".PN.	USPAT	2002/11/22 12:50
6	BRS	1	"4706105".PN.	USPAT	2002/11/22 12:51
7	BRS	1	"5304841".PN.	USPAT	2002/11/22 12:51
8	BRS	1	"5371044".PN.	USPAT	2002/11/22 12:51
9	BRS	1	"5517056".PN.	USPAT	2002/11/22 12:52
10	BRS	1	"5708300".PN.	USPAT	2002/11/22 12:52
11	BRS	1	"5780933".PN.	USPAT	2002/11/22 12:52
12	BRS	1	"5984327".PN.	USPAT	2002/11/22 12:53
13	BRS	8	"5708300"	USPAT; JPO	2002/11/22 12:57
14	BRS	1	"5475259".PN.	USPAT	2002/11/22 12:55
15	BRS	1	"5841192".PN.	USPAT	2002/11/22 12:56
16	BRS	3	08139228.pn. or 09022961.pn. or 09330994.pn.	USPAT; JPO	2002/11/22 12:59
17	BRS	2690	(semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3 or resin) with rib	USPAT; JPO	2002/11/22 13:01
18	BRS	2352	(semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3 or resin) with rib	USPAT	2002/11/22 13:02

	Type	Hits	Search Text	DBs	Time Stamp
19	BRS	45	257/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3 or resin) with rib	USPAT	2002/11/22 13:03
20	BRS	36	257/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib	USPAT	2002/11/22 20:47
21	BRS	11	438/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib	USPAT	2002/11/22 13:16
22	BRS	2036	(semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib not ((257/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib) or (438/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib))	USPAT	2002/11/22 21:33
23	BRS	62	361/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib	USPAT	2002/11/22 13:19

	Type	Hits	Search Text	DBs	Time Stamp
24	BRS	1991	(semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib not ((257/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib) or (438/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib) or (361/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib))	USPAT	2002/11/22 13:25
25	BRS	478	(semiconductor or chip or die or IC) same (mold\$3 or encapsulat\$3) with rib not ((257/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib) or (438/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib) or (361/\$.ccls. and (semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib))	USPAT	2002/11/22 13:39
26	BRS	581	257/788	USPAT	2002/11/22 18:31
27	BRS	0	257/788 and (encapsulat\$3 or mold\$3) with corner near extension	USPAT	2002/11/22 15:04
28	BRS	12	257/788 and (encapsulat\$3 or mold\$3) with extension	USPAT	2002/11/22 14:26

	Type	Hits	Search Text	DBs	Time Stamp
29	BRS	1	"5137479".PN.	USPAT	2002/11/22 15:01
30	BRS	1	"5293065".PN.	USPAT	2002/11/22 15:01
31	BRS	1	"5665296".PN.	USPAT	2002/11/22 15:01
32	BRS	1	"5961912".PN.	USPAT	2002/11/22 15:01
33	BRS	1	"6007317".PN.	USPAT	2002/11/22 15:01
34	BRS	4	"6177724"	USPAT	2002/11/22 15:02
35	BRS	2	(semiconductor or die or chip or IC) and (encapsulat\$3 or mold\$3) with corner near extension	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 16:56
36	BRS	4	5517056.pn. or 6177724.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 15:14
37	BRS	3	(semiconductor or die or chip or IC) and (encapsulat\$3 or mold\$3 or resin) with corner near extension	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 17:36
38	BRS	31	(semiconductor or die or chip or IC) and (encapsulat\$3 or mold\$3) with corner with extension	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 17:45
39	BRS	124	(semiconductor or die or chip or IC) and (encapsulat\$3 or mold\$3) with corner with cover	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 17:46
40	BRS	1	"4301464".PN.	USPAT	2002/11/22 18:23
41	BRS	1	"4701781".PN.	USPAT	2002/11/22 18:24
42	BRS	1	"4897602".PN.	USPAT	2002/11/22 18:24
43	BRS	1	"5198888".PN.	USPAT	2002/11/22 18:24
44	BRS	2	"5473199"	USPAT	2002/11/22 18:32
45	BRS	1918	257/787	USPAT	2002/11/22 20:10

	Type	Hits	Search Text	DBs	Time Stamp
46	BRS	1	"5731231".PN.	USPAT	2002/11/22 18:40
47	BRS	1	"5773895".PN.	USPAT	2002/11/22 18:43
48	BRS	1	"5986695".PN.	USPAT	2002/11/22 18:44
49	BRS	1	"6114189".PN.	USPAT	2002/11/22 18:44
50	BRS	1	"6242287".PN.	USPAT	2002/11/22 18:44
51	BRS	1	"5616958".PN.	USPAT	2002/11/22 19:03
52	BRS	1	"5629566".PN.	USPAT	2002/11/22 19:03
53	BRS	1	"5641996".PN.	USPAT	2002/11/22 19:03
54	BRS	1	"5670826".PN.	USPAT	2002/11/22 19:03
55	BRS	0	5886398.pn. and rib	USPAT	2002/11/22 20:10
56	BRS	1	5886398.pn.	USPAT	2002/11/22 20:47
57	BRS	256	(semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with rib	JPO	2002/11/22 21:33
58	BRS	460	(semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with corner	JPO	2002/11/22 21:33
59	BRS	7	(semiconductor or chip or die or IC) and (mold\$3 or encapsulat\$3) with corner with rib	JPO	2002/11/22 21:34
60	BRS	290	(semiconductor or chip or die or IC) with (mold\$3 or encapsulat\$3) with corner	JPO	2002/11/22 21:34
61	BRS	7	6177724.pn. or 5517056.pn. or 5473199.pn. or 6396708.pn. or 5892289.pn. or 2000114427.pn. or 11176855.pn.	USPAT; JPO	2002/11/22 21:59
62	BRS	1918	257/787	USPAT	2002/11/22 22:49

	Type	Hits	Search Text	DBs	Time Stamp
63	BRS	3807	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 22:49
64	BRS	3	257/787 and (semiconductor or die or chip or IC) and (encapsulat\$3 or mold\$3) with corner with cover	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 22:52
65	BRS	2	6130383.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 22:52

	Document ID	Issue Date	Current OR	Inventor
1 ✓	US 6396708 B1	20020528	361/760	Iguchi, Akihisa
2 ✓	US 6177724 B1	20010123	257/701	Sawai, Akiyoshi
3 ✓	US 5892289 A	19990406	257/783	Tokuno, Kenichi ✓
4 ✓	US 5517056 A	19960514	257/666	Bigler, Charles G. et al.
5 ✓	US 5473199 A	19951205	257/787	Murakami, Yoji
6 ✓	JP 2000114427 A	20000421		TAKAHASHI, NORIYUKI
7 ✓	JP 11176855 A	19990702		INOUE, AKINOBU

	U	1	Document ID	Issue Date	Pages
✓ 1	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6177724 B1	20010123	11
✓ 9	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5517056 A	19960514	11
✓ 15	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5473199 A	19951205	10
✓ 17	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6396708 B1	20020528	11
✓ 20	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5892289 A	19990406	9
✓ 21	<input type="checkbox"/>	<input checked="" type="checkbox"/>	JP 2000114427 A	20000421	10
✓ 22	<input type="checkbox"/>	<input checked="" type="checkbox"/>	JP 11176855 A	19990702	5